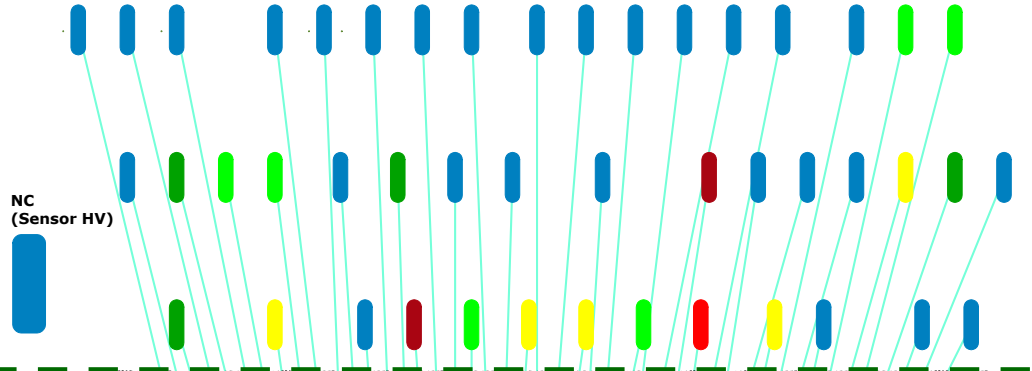


**PCB**  
**Pad Size:  $\sim 89 \times 304 \mu\text{m}$**   
**Min pad spacing  $\sim 200 \mu\text{m}$**   
**Size: 1.7" x 1.8" x 0.062", (12-layers)**  
**ENIG with soft-gold 5-10u in wire-bond area**



**NO Encapsulation**

**Die (Attached by SLAC)**  
**100-micron pitch pads**  
**Pad size:  $60 \times 100 \mu\text{m}$**   
**Die size:  $\sim 5 \times 7 \text{ mm}$**   
**Die thickness:  $700 \mu\text{m}$**

